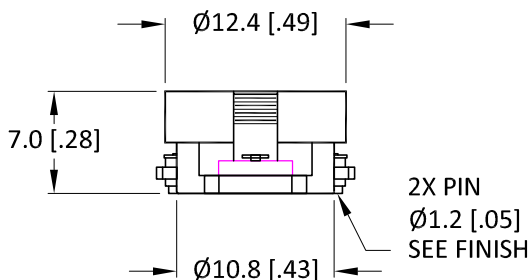
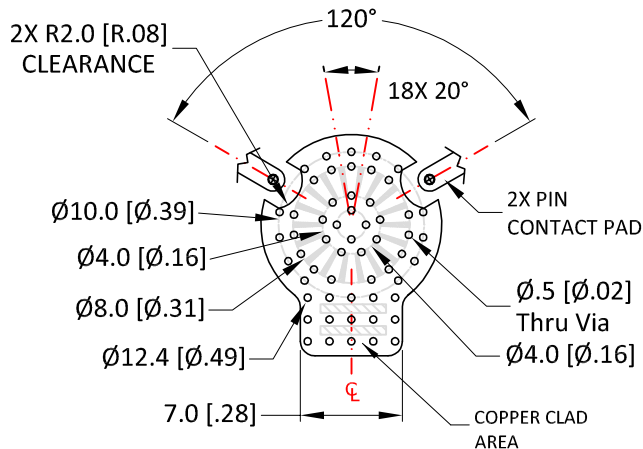
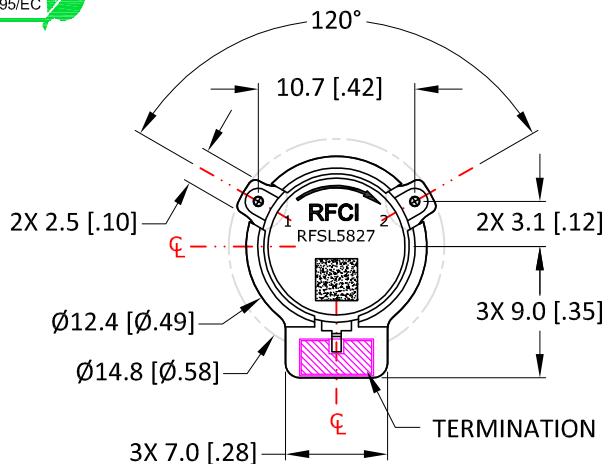


REVISIONS

REV.	DESCRIPTION	ECO	DATE	APPROVED
A	INITIAL RELEASE	I.R.	06/29/15	P.T

THIS DRAWING HAS BEEN GENERATED BY A CAD SYSTEM. CHANGES SHALL ONLY BE INCORPORATED AS DIRECTED BY THE DESIGN ACTIVITY. DO NOT REVISE MANUALLY.



SolderMask Pattern

Recommended Footprint
Copper-SolderMask Pattern

The Land Pattern should be with good thermal conductivity

Finish:

1. Housing: Silver plated
2. Pin: Gold plated
3. Coplanarity specification: 0.10 [0.004] MAX.

Specifications

Parameter	Minimum	Typical	Maximum
Frequency Range (MHz)	2550		2650
Insertion Loss (dB)		< .25	.30
Isolation (dB)	20	> 22	
Return Loss (dB)	20	> 22	

NOTES:

1. Typical Values Represent Performance @ +23 °C.
2. Isolator Flange held to +85°C; 30 Min. maximum Duration.

Power & Temperature Ratings

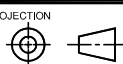
Parameter	Maximum
Forward PWR Peak/AVG	500/50 Watts
Reverse Power CW	10 Watts
Termination Rating (See Note 2)	10 Watts
Operating Temperature	-40 to +85° C
Storage Temperature	-50 to +125° C

CW SMD ISOLATOR MODEL: RFSL5827

UNLESS OTHERWISE SPECIFIED
ALL DIMENSIONS ARE IN MILLIMETERS [INCHES]:

TOLERANCES ARE:

1 PLACE DECIMAL ±.2 [±.01]	ANGULAR: ±1.0°
2 PLACE DECIMAL ±.10 [±.004]	SURFACE ROUGHNESS 16/



APPROVALS DATE

DRAWN BY:

CHECKED BY:

DESIGN BY:

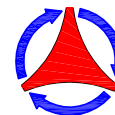
ENGINEER BY:

MFG. ENGR.

Q.A.

PROG. MGMT/MKT

RFCI



TITLE

OUTLINE/SPECS

SIZE
A

CAGE NO.

DWG NO.

SL5827-OS

REV.
A

DO NOT SCALE DRAWING

SCALE: FULL

SHEET 1 OF 1